

Oxfords 81 and 82

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Etch Rates

[Oxford 81 baselines](#)

SOURCE: Abdurrahman Gumus (AFS:Fellows)
DATE: 5/9/2013

[Oxford 82 baselines](#)

SOURCE: Abdurrahman Gumus (AFS:Fellows)
DATE: 3/4/2013

User Recipes

[Oxford 82-Molybdenum etch DOE](#)

SOURCE: (AFS:Staff)
DATE: 9/2/2011

[Oxford 82 - Ar/O2 BARC etch DOE](#)

SOURCE: (AFS:Staff)
DATE: 9/2/2011

Etching Monolayer Graphene

TOOL: Oxford 81/82

SOURCE: Melina Blees (McEuen Group)

ADDED: 2/17/13

10-minute O2 clean (standard recipe) on empty chamber. To etch graphene, use the standard oxygen clean recipe, 20-25s. Any longer and you will cake resist residue on.

Oxygen Etching of Parylene C Films

TOOL: Oxford 81

SOURCE: Ryan Badman, CNF Fellow

ADDED: 1/30/15

5 minute etch or a 10 minute etch etched about 200 nm/min of Parylene in the oxygen clean recipe

If people have thick (microns) parylene they can use 110 deg C ALD SiO2 as an etch mask since photoresist will burn too fast in the oxygen for thicker parylene (roughly same rate as parylene).

IMPORTANT NOTE: *Don't use the Anatech because the parylene film (monomer) melts at 160 deg C.*